ULVAC SOLUTIONS

Optcal Communication Devices

ULVAC Solutions

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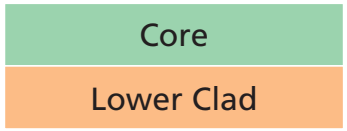
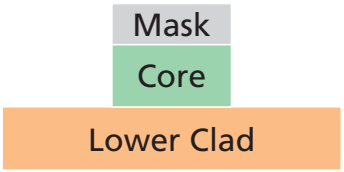
Formation of Clad & Core



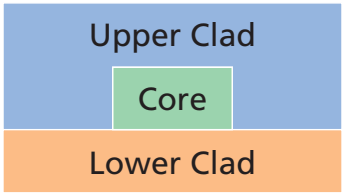
- Formation of Lower Clad & Core Layer
  → **PECVD CME-200**
- Thermal Treatment
  → **Annealer**

Core Layer Etching



- Mask Formation → **Sputter SME-200, Evapoation EBX-1000**
- Mask Etcher → **NE-5500**
- Resist Stripper → **ENVIRO**
- Etcher of Core Layer → **NLD-6000, NLD-800**

Formation of Upper Clad



- Covering of Core Layer
  → **PECVD CME-200**

Clad & Core Deposition

CME-200

Annealing

V6-100

Metal Mask Deposition

SME-200

Mask Etching

NE-5500

Resist Stripping

ENVIRO

Core Layer Etching

NLD-6000

Upper Clad Deposition

CME-200

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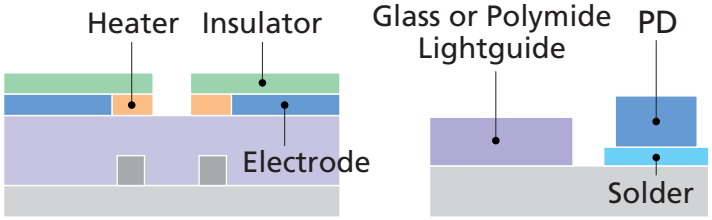
Formation of Electrode, Solder & Heater



Sputtering System for Heat Film, Electrode Film Deposition

SV-4540

Evaporation System for Solder and Electrode Film Deposition

EBX-1000

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Standardized Equipment

PECVD

CME-200

Sputter

SME-200

Etcher

NLD-6000

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1. Cassette to Cassette type Equipment performed small footprint and low price.
2. ø3~8" substrate available (option; unknown size, square substrate)
3. Control System; GPCS (touch panel computer + sequencer) developed by ULVAC
4. Standardization of cassette chamber, transfer chamber and transfer robot etc. in each equipment